



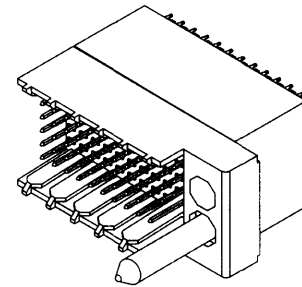
2.00mm (.079") Pitch

HDM*

**Board-to-Board
Stacking Header**

73771

**High Rise Vertical
Press-Fit Guide Pin Option**



FEATURES AND SPECIFICATIONS

Features and Benefits

- For parallel board packaging
- Available in press-fit or solder tail
- Up to 32mm board-to-board stack heights
- Mezzanine card to facilitate blind mate
- Surface Mount Compatible

Reference Information

Product Specification: PS-73670-9999

Packaging: Tube

UL File No.: E29179

Mates With: 73632 and 73780

Designed In: Millimeters

Electrical

Current: 1.0A

Contact Resistance:

Row	A	B	C	D	E	F
mΩ max.	13	18	20	25	30	32

Dielectric Withstanding Voltage: 1000V

Insulation Resistance: 1000 MΩ min.

Mechanical

Insertion Force: 1.35N max. per press-fit pin

Retention Force: 22.5N min. per press-fit pin

Mating Force: 0.35N typical per contact

Unmating Force: 0.15N min.

Signal Normal Force: 0.75N nom./0.60N min.

Durability: 250 cycles

Physical

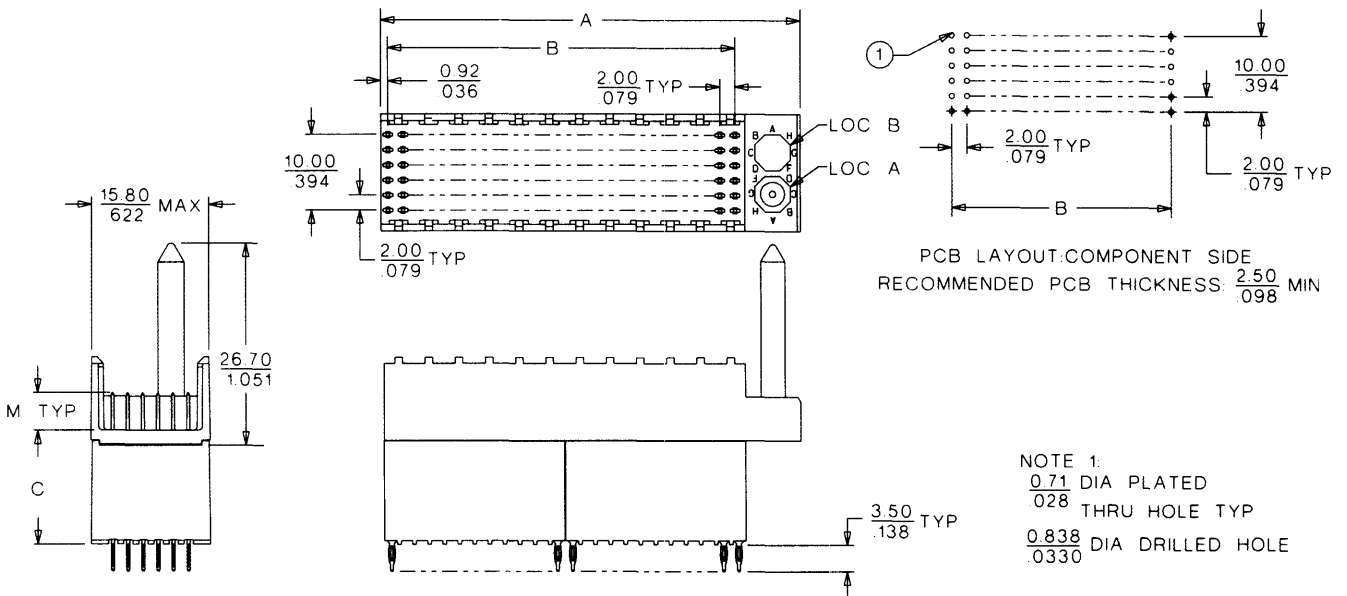
Housing: Liquid crystal polymer

Contact: Phosphor Bronze

Plating: 30μ" Gold

Operating Temperature: -55 to +105°C

CATALOG DRAWING (FOR REFERENCE ONLY)



ORDERING INFORMATION AND DIMENSIONS

Circuits	Order No.	Guide Post Location	Dimension			
			A	B	C	M
72	73771-0100	A	31.60 (1.244)	22.00 (.866)	15.05 (.593)	5.00 (.197)
	73771-0101	B	31.60 (1.244)	22.00 (.866)	15.05 (.593)	5.00 (.197)
	73771-0102	N/A	31.60 (1.244)	22.00 (.866)	15.05 (.593)	5.00 (.197)
	73771-0200	A	31.60 (1.244)	22.00 (.866)	6.05 (.238)	5.00 (.197)
	73771-0201	B	31.60 (1.244)	22.00 (.866)	6.05 (.238)	5.00 (.197)
	73771-0202	N/A	31.60 (1.244)	22.00 (.866)	6.05 (.238)	5.00 (.197)
	73771-0300	A	31.60 (1.244)	22.00 (.866)	10.05 (.396)	5.00 (.197)
	73771-0301	B	31.60 (1.244)	22.00 (.866)	10.05 (.396)	5.00 (.197)
	73771-0302	N/A	31.60 (1.244)	22.00 (.866)	10.05 (.396)	5.00 (.197)
144	73771-1100	A	55.60 (2.189)	46.00 (1.811)	15.05 (.593)	5.00 (.197)
	73771-1101	B	55.60 (2.189)	46.00 (1.811)	15.05 (.593)	5.00 (.197)
	73771-1102	N/A	55.60 (2.189)	46.00 (1.811)	15.05 (.593)	5.00 (.197)
	73771-1200	A	55.60 (2.189)	46.00 (1.811)	6.05 (.238)	5.00 (.197)
	73771-1201	B	55.60 (2.189)	46.00 (1.811)	6.05 (.238)	5.00 (.197)
	73771-1202	N/A	55.60 (2.189)	46.00 (1.811)	6.05 (.238)	5.00 (.197)
	73771-1300	A	55.60 (2.189)	46.00 (1.811)	10.05 (.396)	5.00 (.197)
	73771-1301	B	55.60 (2.189)	46.00 (1.811)	10.05 (.396)	5.00 (.197)
	73771-1302	N/A	55.60 (2.189)	46.00 (1.811)	10.05 (.396)	5.00 (.197)

* High Density Metric and HDM^{PLUS} are trademarks of Teradyne, Inc.
Note: Additional key combinations and locations are available, please contact Molex

Note: The guide pin must mate with the top position on the mating receptacle to clear the board edge. Therefore, if guidepin headers are used on each end of a header array, you should select one with the pin in location B and the second with the guidepin in location A.